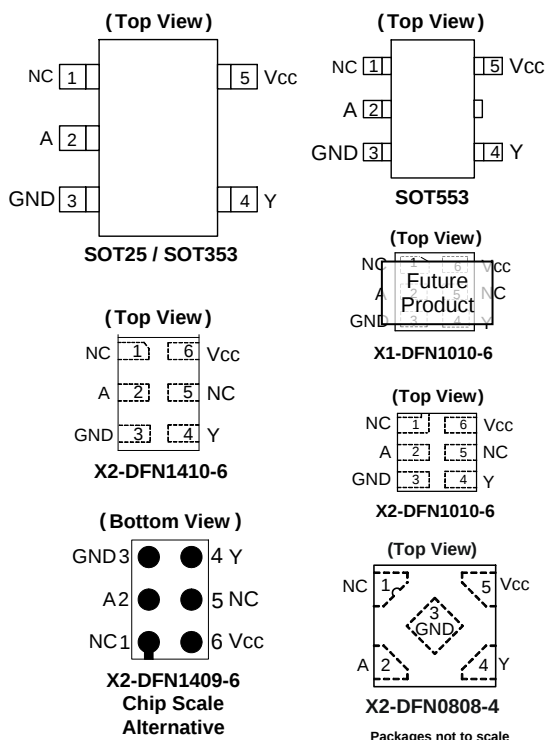


Description

The 74LVC1G17 is a single 1-input Schmitt-trigger buffer with a standard push-pull output. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down. The gate performs the positive Boolean function:

$$Y = A$$

Pin Assignments



Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- $\pm 24\text{mA}$ Output Drive at 3.3V
- CMOS low power consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115)
 - 2,000-V Human Body Model (A114)
 - Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

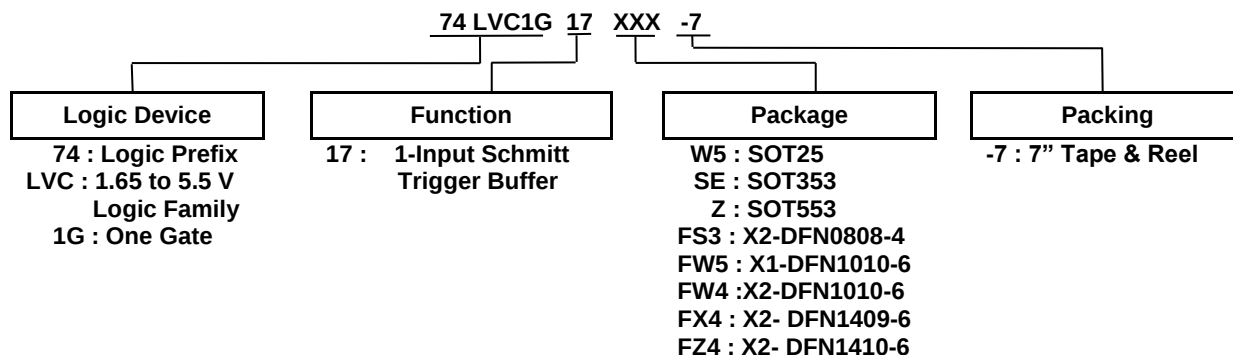
Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of products such as:
 - PCs, networking, notebooks, netbooks, PDAs
 - Computer peripherals, hard drives, CD/DVD ROM
 - TV, DVD, DVR, set top box
 - Cell Phones, Personal Navigation / GPS
 - MP3 players, Cameras, Video Recorders

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and < 1000 ppm antimony compounds.

Ordering Information



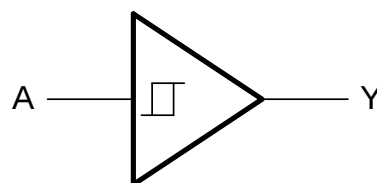
Device	Package Code	Package (Notes 4, 5)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74LVC1G17W5-7	W5	SOT25	3.0mm X 2.8mm X 1.2mm 0.95 mm lead pitch	3,000/Tape & Reel	-7
74LVC1G17SE-7	SE	SOT353	2.0mm X 2.0mm X 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74LVC1G17Z-7	Z	SOT553	1.1.6mm X 1.6 mm X 0.62mm 0.5 mm lead pitch	4,000/Tape & Reel	-7
74LVC1G17FS3-7	FS3	X2-DFN0808-4	0.9mm X 0.9 mm X 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7
74LVC1G17FW5-7 (Future Product)	FW5	X1-DFN1010-6 (Future Product)	1.0mm X 1.0mm X 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G17FW4-7	FW4	X2-DFN1010-6	1.0mm X 1.0mm X 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G17FX4-7	FX4	X2-DFN1409-6 (Chip Scale Alternative)	1.4mm X 0.9mm X 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G17FZ4-7	FZ4	X2-DFN1410-6	1.4mm X 1.0mm X 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes' suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 5. The taping orientation is located on our website at <https://www.diodes.com/assets/Diodes-Packaging/ap02007.pdf>.

Pin Descriptions

Pin Name	Description
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage

Logic Diagram



Function Table

Inputs	Output
A	Y
H	H
L	L

Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High or Low State	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous Output Current	±50	mA
I _{CC} , I _{GND}	Continuous Current through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

- Notes:
6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range..

Recommended Operating Conditions (Note 8)

Symbol	Parameter		Min	Max	Unit
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data retention only	1.5	—	V
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	V _{CC}	V
I _{OH}	High-Level Output current	V _{CC} = 1.65V	—	-4	mA
		V _{CC} = 2.3V	—	-8	
		V _{CC} = 2.7V	—	-12	
		V _{CC} = 3V	—	-16	
			—	-24	
		V _{CC} = 4.5V	—	-32	
I _{OL}	Low-Level Output current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 2.7V	—	12	
		V _{CC} = 3V	—	16	
			—	24	
		V _{CC} = 4.5V	—	32	
T _A	Operating Free-Air Temperature	—	-40	+125	°C

Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (All typical values are at $V_{CC} = 3.3\text{V}$, $T_A = +25^{\circ}\text{C}$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
V_{T+}	Positive-going Input Threshold Voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V_{T-}	Negative-going Input Threshold Voltage	—	1.65V	0.30	—	0.72	—
		—	2.3V	0.58	—	1.00	—
		—	3V	0.80	—	1.30	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.40	—	0.80	—
		—	3V	0.35	—	1.00	—
		—	4.5V	0.55	—	1.10	—
		—	5.5V	0.60	—	1.20	—
V_{OH}	High Level Output Voltage	$I_{OH} = -100\mu\text{A}$	1.65V to 5.5V	$V_{CC} - 0.1$	—	—	V
		$I_{OH} = -4\text{mA}$	1.65V	1.2	—	—	
		$I_{OH} = -8\text{mA}$	2.3V	1.9	—	—	
		$I_{OH} = -12\text{mA}$	2.7V	2.2	—	—	
		$I_{OH} = -16\text{mA}$	3V	2.4	—	—	
		$I_{OH} = -24\text{mA}$		2.3	—	—	
		$I_{OH} = -32\text{mA}$	4.5V	3.8	—	—	
V_{OL}	Low-Level Output Voltage	$I_{OL} = 100\mu\text{A}$	1.65V to 5.5V	—	—	0.1	V
		$I_{OL} = 4\text{mA}$	1.65V	—	—	0.45	
		$I_{OL} = 8\text{mA}$	2.3V	—	—	0.3	
		$I_{OL} = 12\text{mA}$	2.7V	—	—	0.4	
		$I_{OL} = 16\text{mA}$	3V	—	—	0.4	
		$I_{OL} = 24\text{mA}$		—	—	0.55	
		$I_{OL} = 32\text{mA}$	4.5V	—	—	0.55	
I_I	Input Current	$V_I = 5.5\text{V}$ or GND	0 to 5.5V	—	—	± 5	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5\text{V}$	0	—	—	± 10	μA
I_{CC}	Supply Current	$V_I = 5.5\text{V}$ of GND $I_O = 0$	1.65V to 5.5V	—	—	10	μA
ΔI_{CC}	Additional Supply Current	Input at $V_{CC} - 0.6\text{V}$	3V to 5.5V	—	—	500	μA

Electrical Characteristics (@T_A = -40°C to +125°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ.	Max	Unit
V _{T+}	Positive-Going Input Threshold Voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3 V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V _{T-}	Negative-Going Input Threshold Voltage	—	1.65V	0.30	—	0.75	—
		—	2.3V	0.58	—	1.03	—
		—	3V	0.80	—	1.33	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV _T	Hysteresis (V _{T+} - V _{T-})	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.37	—	0.80	—
		—	3V	0.32	—	1.00	—
		—	4.5V	0.50	—	1.20	—
		—	5.5V	0.55	—	1.40	—
V _{OH}	High Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	—	V
		I _{OH} = -4mA	1.65V	0.95	—	—	
		I _{OH} = -8mA	2.3V	1.7	—	—	
		I _{OH} = -12mA	2.7V	1.9	—	—	
		I _{OH} = -16mA	3V	2.2	—	—	
		I _{OH} = -24mA		2.0	—	—	
		I _{OH} = -32mA	4.5V	3.4	—	—	
V _{OL}	High-Level Input Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	—	0.1	V
		I _{OL} = 4mA	1.65V	—	—	0.7	
		I _{OL} = 8mA	2.3V	—	—	0.45	
		I _{OL} = 12mA	2.7V	—	—	0.6	
		I _{OL} = 16mA	3V	—	—	0.6	
		I _{OL} = 24mA		—	—	0.8	
		I _{OL} = 32mA	4.5V	—	—	0.8	
I _I	Input Current	V _I = 5.5 V or GND	0 to 5.5V	—	—	± 100	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	—	± 200	μA
I _{CC}	Supply Current	V _I = 5.5V of GND I _O = 0	1.65V to 5.5V	—	—	200	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} - 0.6 V	3V to 5.5V	—	—	5,000	μA

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 9)	—	204	—	$^\circ C/W$
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 9)	—	52	—	$^\circ C/W$
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 9. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^\circ C$ to $+85^\circ C$, $C_L = 15pF$ as noted (See Figure 1)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	1.0	9.9	0.7	5.5	0.7	4.6	0.7	4.4	ns

$T_A = -40^\circ C$ to $+85^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 2)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	1.0	11	0.7	6.5	0.7	5.5	0.7	5	ns

$T_A = -40^\circ C$ to $+125^\circ C$, $C_L = 15 pF$ as noted (See Figure 1)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	1.0	12.5	0.7	7.5	0.7	6.5	0.7	5.5	ns

$T_A = -40^\circ C$ to $+125^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 2)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	1.0	14.0	0.7	8.5	0.7	7.0	0.7	6.5	ns

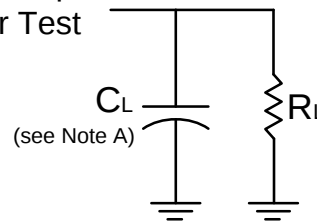
Operating Characteristics

$T_A = +25^\circ\text{C}$

Parameter		Test Conditions	$V_{CC} = 1.8\text{V}$	$V_{CC} = 2.5\text{V}$	$V_{CC} = 3.3\text{V}$	$V_{CC} = 5\text{V}$	Unit
			Typ.	Typ.	Typ.	Typ.	
C_{PD}	Power Dissipation Capacitance	$f = 10\text{ MHz}$	20	22	23	25	pF

Parameter Measurement Information

From Output
Under Test



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_R/t_F			
$1.8\text{V} \pm 0.15\text{V}$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	15pF	1M Ω
$2.5\text{V} \pm 0.2\text{V}$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	15pF	1M Ω
$3.3\text{V} \pm 0.3\text{V}$	3V	$\leq 2.5\text{ns}$	1.5V	15pF	1M Ω
$5\text{V} \pm 0.5\text{V}$	V_{CC}	$\leq 2.5\text{ns}$	$V_{CC}/2$	15pF	1M Ω

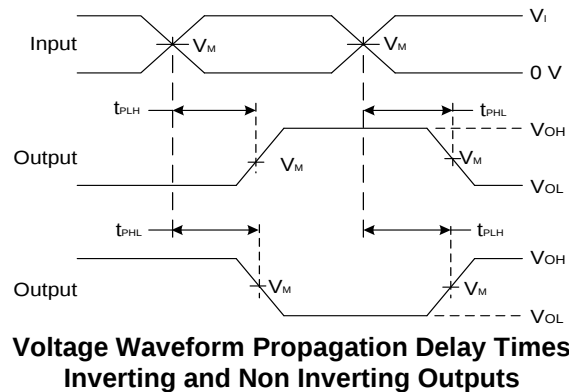
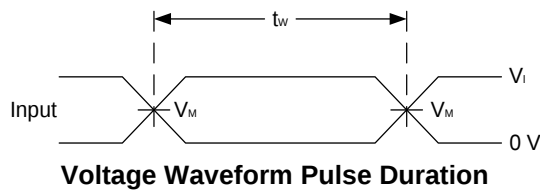
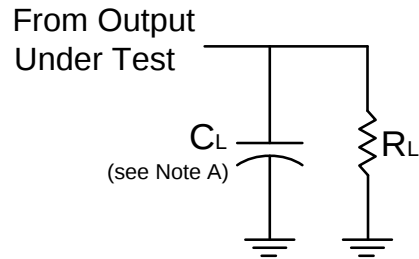


Figure 1. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10\text{MHz}$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Parameter Measurement Information (Continued)



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_R/t_F			
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	1k Ω
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	500 Ω
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	50pF	500 Ω
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	50pF	500 Ω

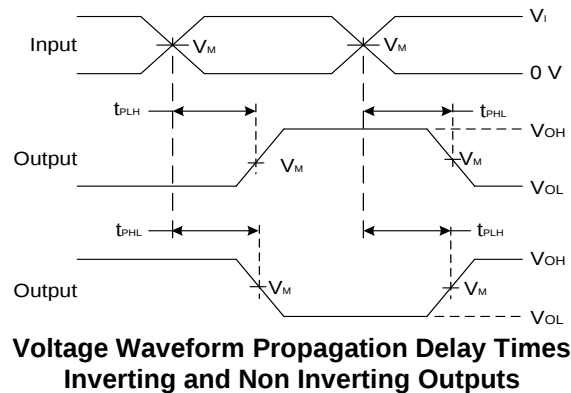
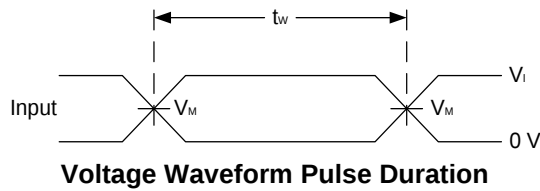
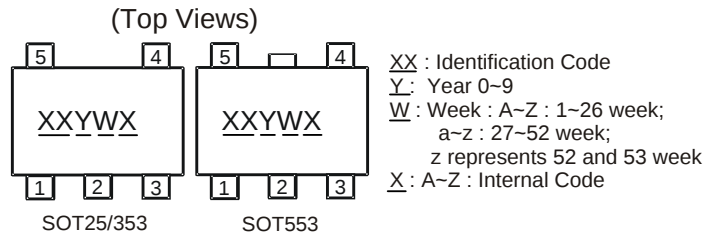


Figure 2. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

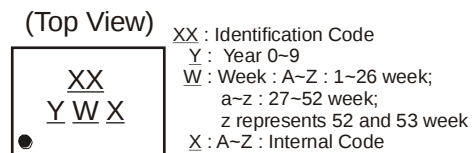
Marking Information

(1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G17W5-7	SOT25	UR
74LVC1G17SE-7	SOT353	UR
74LVC1G17Z-7	SOT553	UR

(2) DFN packages

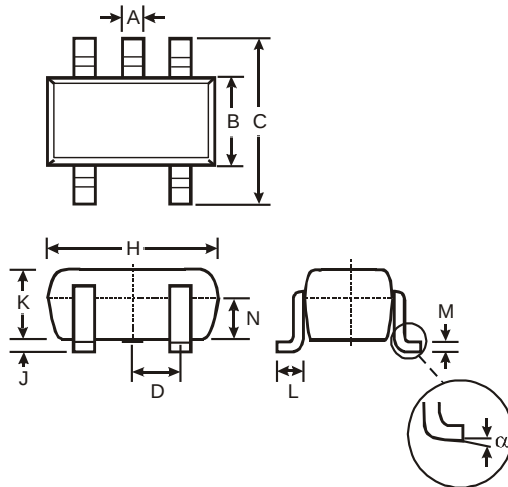


Part Number	Package	Identification Code
74LVC1G17FS3-7	X2-DFN0808-4	WR
74LVC1G17FW5-7	X1-DFN1010-6	V9
74LVC1G17FW4-7	X2-DFN1010-6	UR
74LVC1G17FX4-7	X2-DFN1409-6	MH
74LVC1G17FZ4-7	X2-DFN1410-6	UR

Package Outline Dimensions

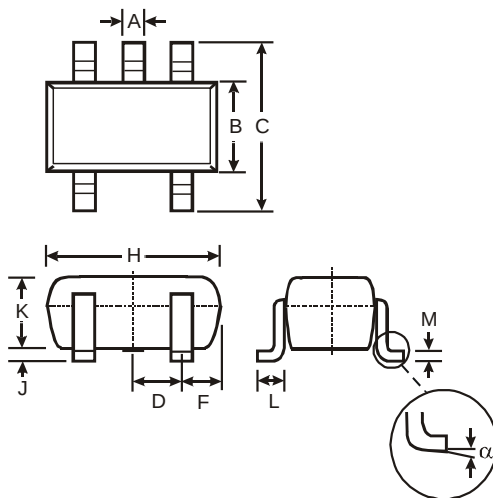
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SOT25



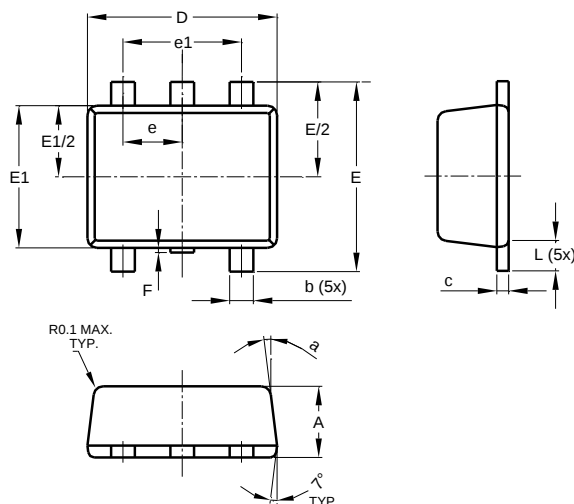
SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	—
All Dimensions in mm			

(2) Package Type: SOT353



SOT353		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

(3) Package Type: SOT553

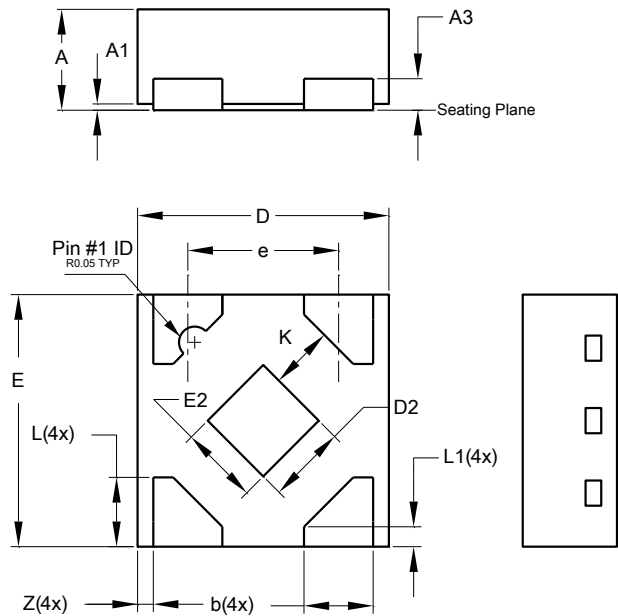


SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
α	6°	8°	7°
All Dimensions in mm			

Package Outline Dimensions (Continued)

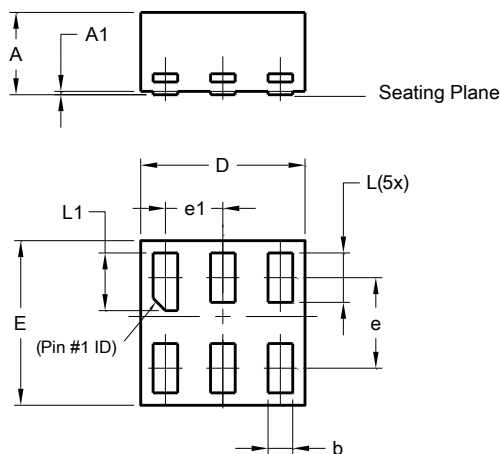
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4) Package Type X2-DFN0808-4



X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
K	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
Z	-	-	0.05
All Dimensions in mm			

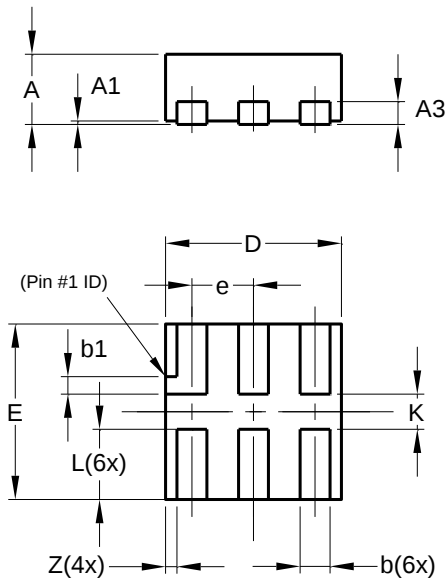
(5) Package Type: X1-DFN1010-6



X1-DFN1010-6			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.55 BSC		
e1	0.35 BSC		
L	0.27	0.35	0.30
L1	0.32	0.40	0.35
All Dimensions in mm			

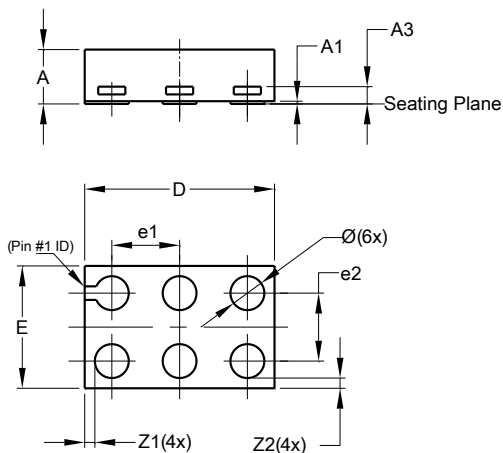
Package Outline Dimensions (Cont.)

(6) Package Type X2-DFN1010-6



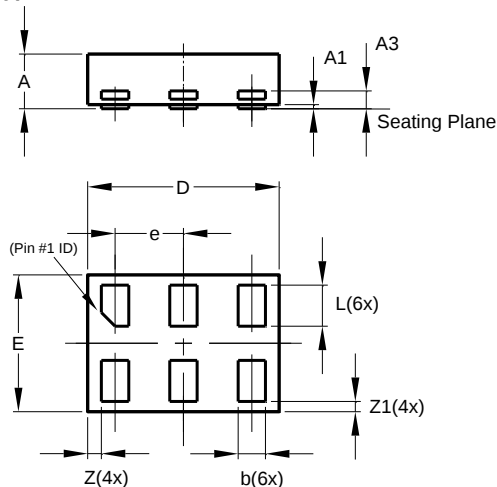
X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

(7) Package Type: X2-DFN1409-6 (Chip Scale Alternative)



X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075
All Dimensions in mm			

(8) Package Type: X2-DFN1410-6

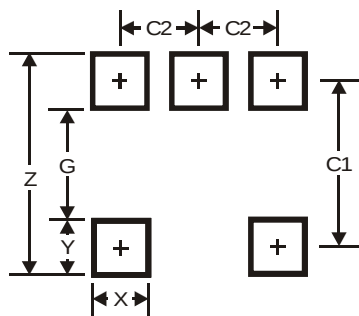


X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

Suggested Pad Layout

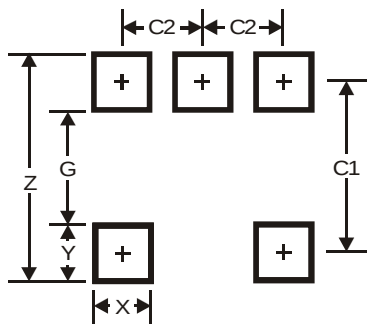
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SOT25



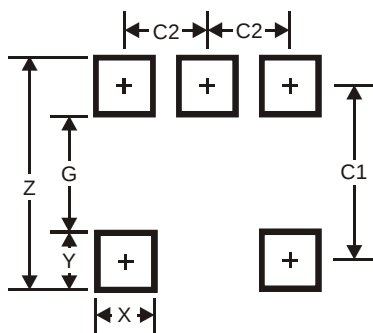
Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: SOT353



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

(3) Package Type: SOT553

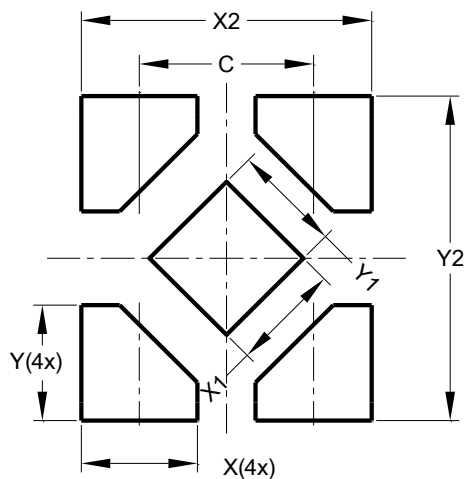


Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

Suggested Pad Layout (Continued)

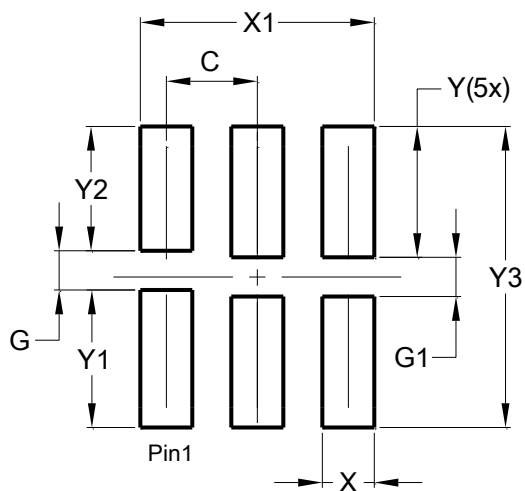
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4) Package Type X2-DFN0808-4



Dimensions	Value (in mm)
C	0.480
X	0.320
X1	0.300
X2	0.800
Y	0.320
Y1	0.300
Y2	0.900

(5) Package Type X1-DFN1010-6

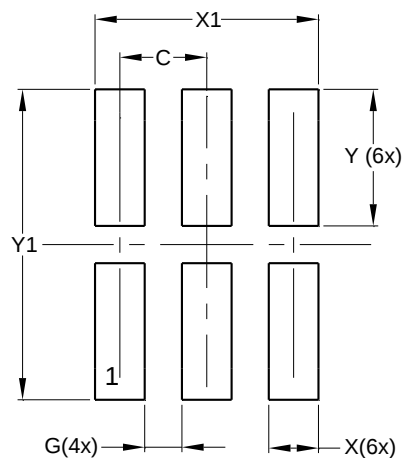


Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

Suggested Pad Layout (Cont.)

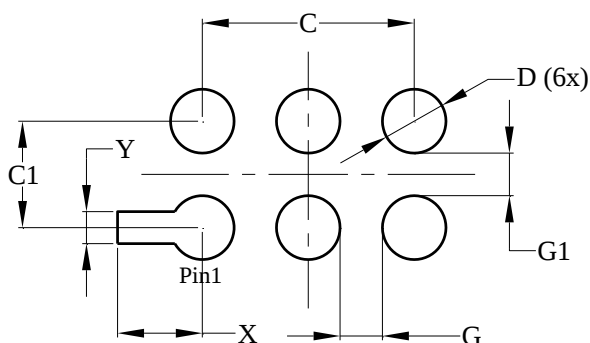
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(6) Package Type X2-DFN1010-6



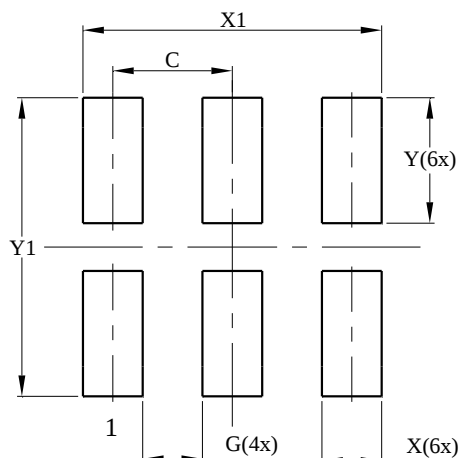
Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

(7) Package Type: X2-DFN1409-6 (Chip Scale Alternative)



Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

(8) Package Type: X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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